

Title (en)

Embedded chip packages and methods for manufacturing an embedded chip package

Title (de)

Eingebettete Chipgehäuse und Verfahren zur Herstellung eines eingebetteten Chipgehäuses

Title (fr)

Boîtiers de puce intégré et procédés de fabrication d'un tel boîtier

Publication

EP 2722876 A2 20140423 (EN)

Application

EP 13189068 A 20131017

Priority

- EP 12007249 A 20121019
- US 201313736097 A 20130108
- EP 13189068 A 20131017

Abstract (en)

A method for manufacturing an embedded chip package is provided. The method may include: forming electrically conductive lines (312) over a substrate (314); placing the substrate next to a chip arrangement comprising a chip (326), the chip comprising one or more contact pads (328), wherein one or more of the electrically conductive lines are arranged proximate to a side wall (332) of the chip; and forming one or more electrical interconnects (342) over the chip arrangement to electrically connect at least one electrically conductive line (312) to at least one contact pad (328).

IPC 8 full level

H01L 23/538 (2006.01)

CPC (source: EP)

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Cited by

DE102015121044A1; DE102015121044B4; US10217695B2; WO2016100267A1

Designated contracting state (EPC)

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